

# SoundBonding application

〈各種金属のインゴット合金三次元接合〉

ハーメチック封止接合

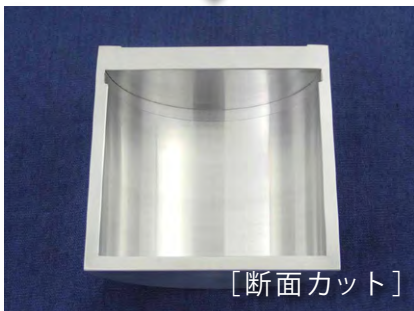
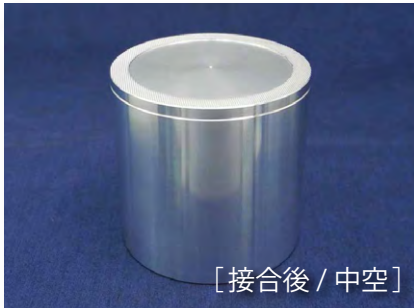
**3DBonding** (Patents pending)



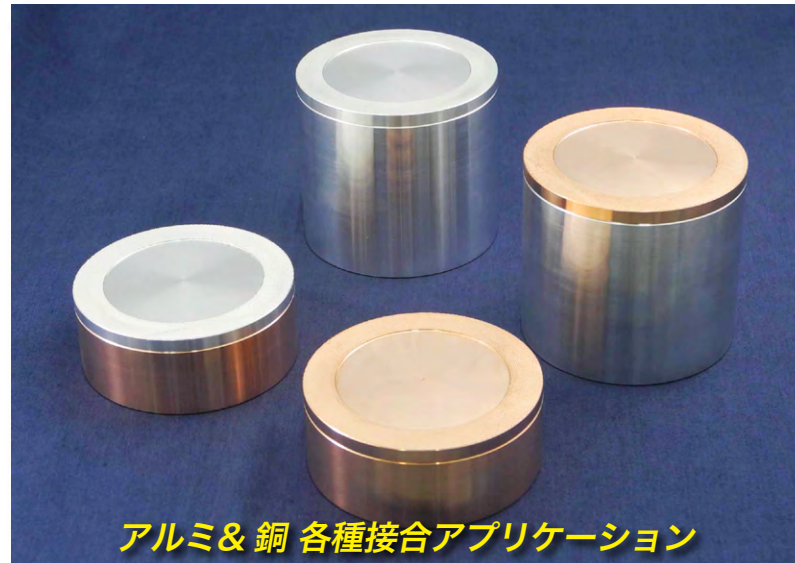
[アルミ材料 A1070]  
〈蓋〉 od=54 t=6mm  
〈本体〉 od=54 id=48 h=50mm t=3mm



[蓋と本体] の 1 秒以下の瞬間接合 !!

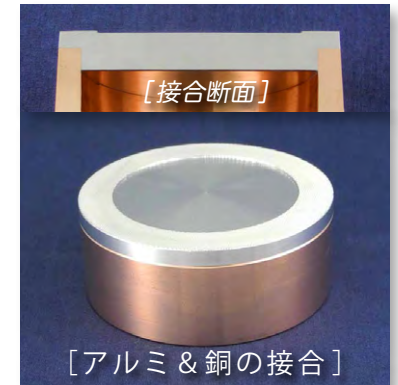
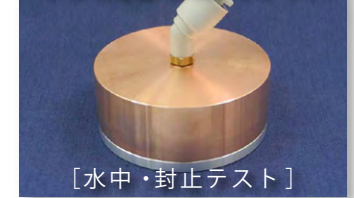


〈接合痕が無い〉

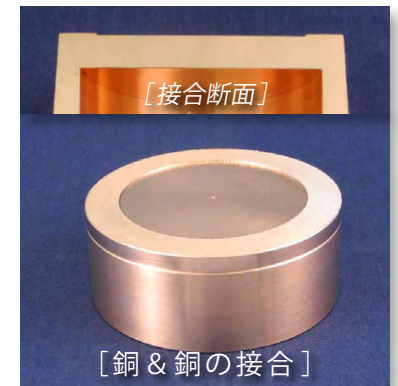


**ECB**

アルミ&銅 0.4MPa クリア



〈合金〉



〈インゴット〉

**ULTEX**  
SoundPower Laboratory